#### PATENT ASSIGNMENT

### Electronic Version v1.1 Stylesheet Version v1.1

**SUBMISSION TYPE: NEW ASSIGNMENT** 

NATURE OF CONVEYANCE: **ASSIGNMENT** 

#### **CONVEYING PARTY DATA**

Name	Execution Date
SEONG CHEOL KIM	06/18/2010

#### **RECEIVING PARTY DATA**

Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	SAN 136-1, AMI-RI, BUBAL-EUP, ICHEON-SI
City:	GYEONGGI-DO
State/Country:	REPUBLIC OF KOREA

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12835927

#### **CORRESPONDENCE DATA**

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NAME OF SUBMITTER: Brian W. Hameder

Total Attachments: 2

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> **PATENT** REEL: 024691 FRAME: 0493

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## UNITED STATES OF AMERICA ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

#### **ASSIGNOR:**

Name: Seong Cheol KIM

Address: 101-402, Iljuk IC Town, Iljuk-myeon, Anseong-si, Gyeonggi-do, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

**ASSIGNEE:** 

Name: Hynix Semiconductor Inc.

Address: San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

# SEMICONDUCTOR CHIP AND SEMICONDUCTOR PACKAGE INCLUDING THE SAME

(TITLE)

and which is found in (check one applicable item below)	
U.S. patent application executed on even date he	erewith
U.S. Application Serial No.	filed on

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby convenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further convenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same

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in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

Seong Cheol Kim
INVENTOR: Seong Cheol KIM

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**RECORDED: 07/15/2010** 

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